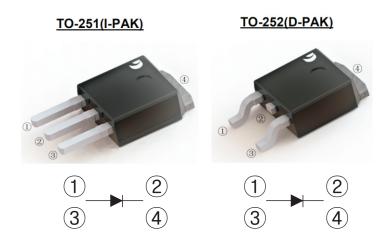
### G401xY THRU G410xY

### GLASS PASSIVATED RECTIFIERS Reverse Voltage - 100 to 1000 V

Forward Current - 4.0 A

#### **FEATURES**

- High current capability
- Low forward voltage drop
- Low power loss, high efficiency
- High surge capability
- · High temperature soldering guaranteed
- Mounting position: any



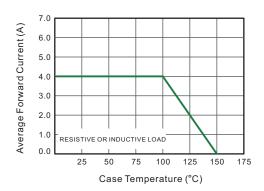
# MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS Ratings at 25°C ambient temperature unless otherwise specified

CHARACTERISTICS	TO-251	G401VY	G402VY	G404VY	G406VY	G408VY	G410VY					
CHARACTERISTICS	TO-252	G401DY	G402DY	G404DY	G406DY	G408DY	G410DY	- Units				
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	100	200	400	600	800	1000	V				
Maximum RMS voltage	$V_{RMS}$	70	140	280	420	560	700	V				
Maximum DC Blocking Voltage	V <sub>DC</sub>	100	200	400	600	800	1000	V				
Maximum Average Forward Rectified Current	I <sub>F(AV)</sub>	4.0										
Peak Forward Surge Current,8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	If Sine-wave Superimposed I <sub>FSM</sub> 140											
Max Instantaneous Forward Voltage at 4 A DC	$V_{F}$	V <sub>F</sub> 1.1										
Maximum DC Reverse Current $T_a = 25$ °C at Rated DC Reverse Voltage $T_a = 125$ °C												
Typical Junction Capacitance (1)	C <sub>j</sub>	50										
Typical Thermal Resistance (2)	R <sub>eJC</sub>	50										
Operating Junction Temperature Range	Junction Temperature Range T <sub>j</sub> -55 ∼ +150							°C				
Storage Temperature Range	$T_{stg}$	-55 ~ +150										

<sup>(1)</sup> Measured at 1 MHz and applied reverse voltage of 4 V D.C

<sup>(2)</sup> P.C.B. mounted with 10cmX10cmX1mm copper pad areas.





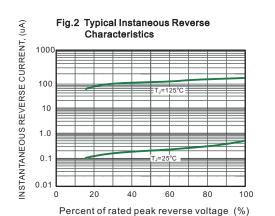


Fig.3 Typical Forward Characteristic

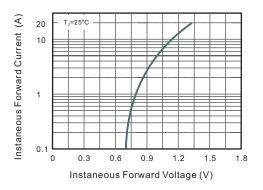


Fig.4 Typical Junction Capacitance

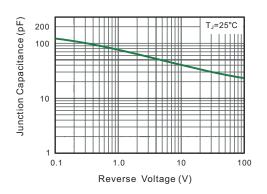


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

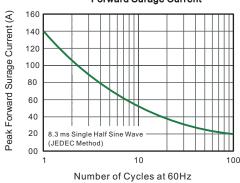
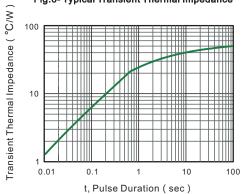
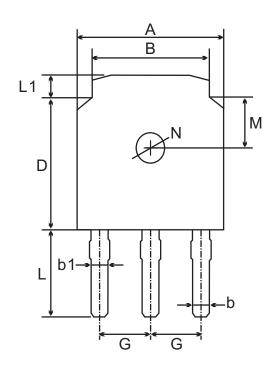
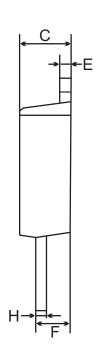


Fig.6- Typical Transient Thermal Impedance



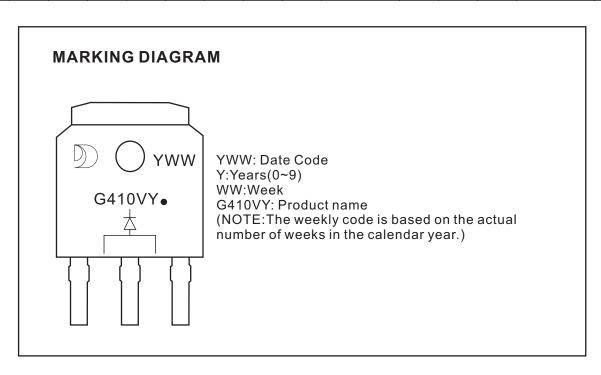
## TO-251(I-PAK) Package Outline Dimensions



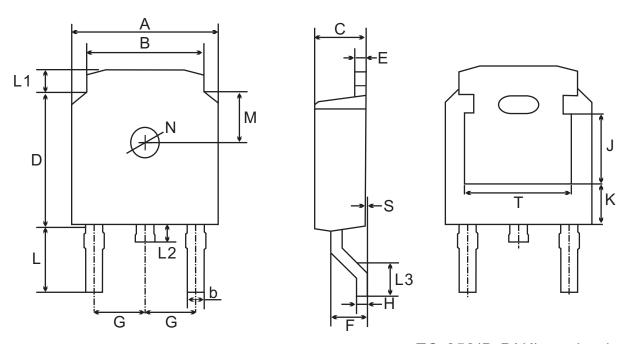


### TO-251(I-PAK) mechanical data

UN	VIT	Α	В	b	b1	С	D	Е	F	G	Н	L	L1	М	N	
mm	max	6.7	5.5	0.86	0.9	2.5	6.3	0.6	1.8	2.29	0.55	4.3	1.2	1.8	1.3 TYPICAL	
"""	min	6.3	5.1	0.66	0.76	2.1	5.9	0.4	1.3	TYPICAL	0.45	3.9	0.8	TYPICAL		
mil	max	264	217	34	35	98	248	24	71	90	22	169	47	71	51	
mil	min	248	201	26	30	83	232	16	51	TYPICAL	18	154	31	TYPICAL	TYPICAL	

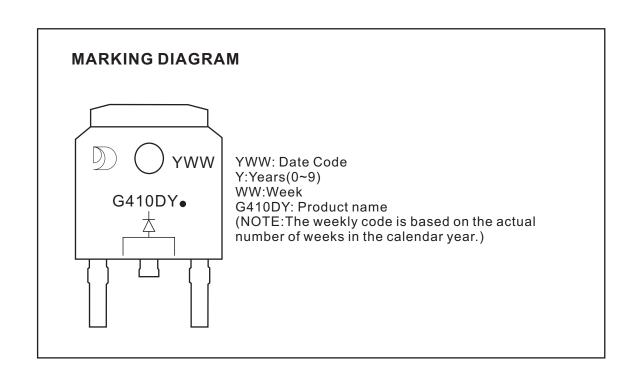


## TO-252(D-PAK) Package Outline Dimensions



#### TO-252(D-PAK) mechanical data

U	VIT	Α	В	b	С	D	Е	F	G	Н	L	L1	L2	L3	S	М	N	J	K	Т
	max								2.29					1.75		1.0				4.83 ref.
mm	min	6.3	5.1	0.66	2.1	5.9	0.4	1.3	TYPICAL	0.45	2.7	8.0	0.6	1.40	0.0					
mil	max	264	217	34	98	248	24	71	90	22	122	47	39	69	4	71	51	124	71	190
	min	248	201	26	83	232	16	51	, F	18	106	31	24	55	0	TYPICAL	TYPICAL	ref.	ref.	ref.



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